

PCN Number:	20170112000	PCN Date:	January 17, 2017
Title:	Datasheet for LMV712-N/LMV712-N-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.



LMV712-N, LMV712-N-Q1

SNOS534J – FEBRUARY 2001 – REVISED NOVEMBER 2016

www.ti.com

Changes from Revision I (January 2014) to Revision J

Page

- Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section 1
- Deleted Soldering specification from Absolute Maximum Ratings table 6
- Changed Thermal Resistance values in Thermal Information table From: 196 To: 84.1 (DSBGA), From: 53.4 To: 70 (WSON), and From: 235 To: 176.8 (VSSOP) 6

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMV712-N/LMV712-N-Q1	SNOS534I	SNOS534J

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/lit/ds/symlink/lmv712-n.pdf>

Reason for Change:

To accurately reflect device thermal characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMV712LD/NOPB	LMV712MM/NOPB	LMV712Q1MMX/NOPB
LMV712LDX/NOPB	LMV712MMX/NOPB	LMV712TL/NOPB
LMV712MM	LMV712Q1MM/NOPB	LMV712TLX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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